# **User Manual**

**PRODUCT NAME :** 802.11a/b/g/n/ac + Bluetooth Combo Module **MODEL NAME** TWCM-B202D 2

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### 1. Features

TWCM-B202D is the small size and low power module for IEEE 802.11ac wireless LAN & BT4.1 + HS. TWCM-B202D is based on Broadcom BCM43569 solution.

- IEEE 802.11 a/b/g/n/ac Dual Band WLAN infrastructure
- Bluetooth 4.1 + HS
- Size : 100.0mm x 17.0mm x 8.4mm
- Two stream spatial multiplexing up to 300Mbps(802.11n)/ 867Mbps(802.11ac)
- Single-and dual-antenna Support
  - Two metal pressed antenna for WLAN and one external antenna for BT
- Use on-chip OTP (One-Time Programmable)
- Host Interface : USB2.0 (WLAN & BT)
  - This model is using the common USB2.0 to control WLAN and BT
- Security : WAPI, WEP, WPA, WPA2, WMM, AES, WEP, TKIP, CKP
- Application: DTV, DVR, HD DVD Player, Blue-ray Disk Player, STB

## 2. Module Photo

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## 3. Block Diagram



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### 4. Storage Conditions

Caution : The specifications in Table 1 define levels at which permanent damage to the device can occur. Function operation is not guaranteed under these conditions. Operating at absolute maximum conditions for extend periods can adversely affect the long-term reliability of the device.

Parameter	Min	Max	Unit
Storage Temperature	-10	+70	°C
Storage Humidity (40°C)	-	90	%

< Table 1 >

- . Other conditions
  - Do not use or store modules in the corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are contained.
     Also, avoid exposure to moisture.
  - 2) Store the modules where the temperature and relative humidity do not exceed 5 to 40°C and 20 to 60%.
  - Assemble the modules within 6 months.
     Check the soldering ability in case of 6 months over.

## 5. Operating Conditions

Parameter	Min	Тур	Мах	Unit
Ambient Temperature	0	-	55	°C
Ambient Humidity (40°C)	-	-	85	%
Supply Voltage	4.75	5	5.25	Vdc

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### 6. Power-up Sequence

- For both the WL\_REG\_ON and BT\_REG\_ON pins, there should be at least a 10ms time delay between consecutive toggles(where both signals have been driven low). This is to allow time for the CBUCK regulator to discharge. If this delay is not followed, then there may be a VDDIO in-rush current on the order of 36mA during the next PMU cold start.
- The BCM43569 has an internal power-on reset(POR) circuit. The device will be held in reset for a maximum of 110ms after VDDC and VDDIO have both passed the POR threshold.
- VBAT should not rise 10%-90% faster than 40 microseconds. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high

32.678 kH Seep Clock VBAT VDU/ - 2 Steep cycles - 2 Steep cyc		
Steep Clock VBAT VDIO VL_REG_ON T_REG_ON NUCRES 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	32.678 kHz	
VLREG_ON *T_REG_ON *Tores 1. YBAT should not rise 10%-90% faster than 40 microseconds. 2. YBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	Sleep Clock	
VBAT VDOID *2 Sleep cycles *T_REG_ON *Notes: 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	/*	
vDi0       ~ 2 Sleep cycles         vL_REG_ON       *Notes:         1. VBAT should not rise 10%-90% faster than 40 microseconds.         2. VBAT should be up before or at the same time as VDDI0. VDDI0 should NOT be present first or be held high before VBAT is high.	VBAT*	90% of VH
VODIO VN_REG_ON BT_REG_ON PTOREE 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	-	
vL_REG_ON *NcREG_ON *Notes: 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.		
VL_REG_ON *Notes: 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	/	~ 2 Sleep cycles
VL_REG_ON *Notes: 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	-	→//
#Notes:         1. VBAT should not rise 10%—90% faster than 40 microseconds.         2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	WL_REG_ON	l l
BT_REG_ON  •Notes:  • VBAT should not rise 10%-90% faster than 40 microseconds.  • VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.		
*Notes: 1. VBAT should not rise 10%-90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO, VDDIO should NOT be present first or be held high before VBAT is high.	PT REG ON	X
*Notes: 1. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.	b1_120_014	/I
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before VBAT is high.	1. VBAT shoul 2. VBAT shoul	d not rise 10%–90% faster than 40 microseconds. d he up before or at the same time as VDDIO. VDDIO should NOT he present first or he held high
	before VBAT is	s high.
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< WLAN = ON, Bluetooth = ON >

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## 7. Pin Description

Pin No.	Pin Name	I/O	Pin Description
1	VCC	I	+5V
2	WLAN_USB_D-	I/O	USB Communication signal USB_DN
3	WLAN_USB_D+	I/O	USB Communication signal USB_DP
4	GND	-	Ground
5	BT_REG_ON		BT Reset
6	BT_HOST_WAKE	0	BT_HOST wake up
7	BT_DEV_WAKE		BT_DEV wake up
8	N.C	-	N.C
9	WLAN _REG_ON	I	WLAN Reset
10	WLAN _HOST_WAKE	0	WLAN_HOST wake up
11	WLAN _DEV_WAKE	I	WLAN_DEV wake up
12	GND	-	Ground





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This device complies with p (1) This c (2) This c may ca	part 15 of the FCC Results. Oper device may not cause harmful int device must accept any interferen use undesired operation.	ation is subject to th terface, and nce received, includ	e following two conditions :
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cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try correct the interference by one or more of the following measures:

- 1.1. Reorient or relocate the receiving antenna.
- 1.2. Increase the separation between the equipment and receiver.
- 1.3. Connect the equipment into an outlet on a circuit different from that to which receiver is connected.
- 1.4. Consult the dealer or experienced radio/TV technician for help.

#### WARNING

Changes or modifications not expressly approved by the manufacturer could void the user's authority to operate the equipment.

#### IC Information

This device complies with Industry Canada license-exempt RSS standard(s). Operation in subject to The following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Cet appareil est conforme avec Industrie Canada RSS standard exempts de licence(s), Son utilisation est soumise à Les deux conditions suivantes: (1) cet appareil ne peut pas provoquer d'interférences et (2) cet appareil doit accepter Toute interférence, y compris les interférences qui peuvent causer un mauvais fonctionnement du dispositif.

#### Information for OEM Integrator

This device is intended only for OEM integrators under the following conditions:

- 1) The antenna must be installed such that 20 cm is maintained between the antenna and users, and
- 2) The transmitter module may not be co-located with any other transmitter or antenna.
- Antenna characteristic.

### WLAN

- Antenna Type : Metal press type
- Frequency Range : 2.40 GHz ~ 2.50 GHz, 5 GHz ~ 6 GHz
- Max peak gain : 2 GHz : 2.5 dBi, 5 GHz : 2.9 dBi
- Impedence : 50 ohm

Bluetooth, Bluetooth LE

- Antenna Type : Metal (Sus, Ni) type
- Frequency Range : 2.4 GHz ~ 2.5 GHz
- Max peak gain : 0.42 dBi
- Impedence : 50 ohm

End product labelling The label for end product must include "Contains FCC ID: YZP-TWCMB202D, IC ID: 7414C-TWCMB202D".

#### "CAUTION : Exposure to Radio Frequency Radiation.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment must be installed and operated with minimum distance of 20cm between the radiator and your body. This transmitter module is authorized only for use in device where the antenna may be installed such that 20 cm may be maintained between the antenna and users."